



HDFC BANK OF SRI LANKA

REQUEST FOR PROPOSALS

Name of the Project : Supply, Installation, Commissioning, Training and Maintenance of New Hardware for Core Banking System for the HDFC Bank of Sri Lanka.

Reference No : HDFCB/AD/PRO/RFP/S/2021/06/ 01

HDFC Bank of Sri Lanka call proposals for Supply, Installation, Commissioning, Training and Maintenance of New Hardware for Core Banking System.

The proposal:

- HDFC Bank intends to replace the existing Hardware infrastructure of Core Banking system. Core banking application is based on Oracle Weblogic application server and Oracle database. The new infrastructure is required for the production site and the existing environment is planned to move to DR site.

The detailed scope of work, proposal submission procedure and other related information set out by the HDFC Bank, is available on the HDFC Bank website www.hdfc.lk quick link, "Information on the Proposal".

The Request for Proposal (RFP) documents could be collected from the office of Manager – Administration, HDFC Bank between 9.00 am to 02.30pm on normal working days from 14th June 2021 to 02nd July 2021 upon the payment of a non-refundable Tender Fee of Rs. 2,000.00 and on the submission of a written request for documents on a business letterhead with contact details.

RFP Documents can also be obtained by sending an email to seniorexe.adm@hdfc.lk or admin1@hdfc.lk with the proof of payment. *(Deposits can be done through Sampath Bank Head Quarters A/C No: 002960001977 giving the Narration of "New Hardware for Core Banking System")*

Interested vendors may request clarifications on the "Request for Proposals" via email teccom@hdfc.lk up to 3.00pm, 13th July 2021.

Dully completed proposals should be delivered to the following address by hand or by registered post on or before 2.00pm 26th July 2021.

**Manager – Administration,
HDFC Bank, PO Box 2085, Sir Chittampalam A Gardiner Mawatha, Colombo 02.**

SCOPE OF RFP DOCUMENT

The scope of this RFP is for Supply, Installation, Commissioning, Training and Maintenance of new hardware for Core banking system.

The proposal:

1. Existing hardware of Core banking system replace with the new hardware solution.
2. The existing hardware should be set up at DR site.

Existing Product Environment

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|------|---------------------------|--|
| I. | Operating System | : Oracle Linux 6.6 |
| II. | Server technology | : 3 Intel base 2 socket servers (each 16 core, 128GB,
2 x 8Gbps FC HBA) |
| III. | Virtualization Technology | : Oracle VM 3.4 |
| IV. | Storage Environment | : 8Gbps SAN with Fiber channel Storage (5TB effective capacities) |
| V. | Database | : Oracle Database 11GR2 with RAC. (2 x VMs) Data guard enabled |
| VI. | Application Servers | : Oracle Weblogic 10.3.0.6 |

High-level business requirement

1. Hardware requirement for production environment is as per the technical specification.
 2. Upgrade existing Oracle 11GR2 to Oracle database 19C.
 3. Move existing hardware to DR and upgrade VM/OS suite to propose production solution.
 4. Oracle Database shall be replicated via Oracle Data Guard.
 5. Virtualization technology shall be supported/certified for Oracle database and virtualization technology shall be recognized by Oracle licenses boundaries for Oracle Licenses. (proof of document from Oracle)
 6. Solution shall support Linux, Microsoft Windows Operating systems
 7. All Infrastructure hardware, system and OS shall have 24 x 7 support/subscription from OEM and Local support
 8. Solution should be able to provide Kubernetes and Docker environment which support cloud native computing foundation. (CNCF)
 9. Configure all servers/storages (moved to DR site) and existing servers/storages in DR site and install and configure virtualization and operating system.
3. HDFC Bank intends to procure the solution with the following terms
 - I. The devices should have comprehensive onsite support for a period of 5 years from the date of acceptance given to the Bidder.

- II. The equipment quoted by bidder should not be declared as End of life (EOL) or End of Sale (EOS) by the OEM (Original Equipment Manufacturer) at the time of bidding RFP & also it should not become EOS (End of Support) during first 5 years and in case OEM status does change, then the bidder should upgrade/replace the same free of charge.
 - III. The bidder should migrate to new setup with no/minimum possible downtime.
 - IV. The bidder should provide OEM product training.
4. The bidder should submit the solution architecture with the entire components, and this should include detailed description about the solution including the architecture diagram.
 5. The bidder should responsible for implementing the solution without any impact for the business operations.
 6. The bidder should submit the OEM/Manufacturer Authorization Letter.
 7. The bidder should submit Bill of Material (without finance) including all the part numbers and Quantities in the table format along with the Technical Proposal. The line items on the bill of material that is submitted with the Technical proposal should exactly match with the Bill of material in the Finance Proposal.
 8. The bidder should submit a general description of the techniques, approaches and methods to be used in completing the project.
 9. The bidder shall submit the project plan in MS project (MPP based)
 10. The bidder should provide a user guide on specific customization carried out on HDFC Bank environment.
 11. The bidder should submit at least 1 (one) similar (same proposed product) projects experience during the last 2 (Two) years of the Implementation Partner.
 12. The bidder should submit qualification of Engineer and the Team handling the project.
 13. The selected Bidder shall appoint a single point of contact, with whom HDFC Bank will deal with, for any activity pertaining to the requirements of this RFP.
 14. The proposal for aforesaid scope should be submitted in two sealed envelopes consisting of the following. Based on our RFP technical template, vendor should be able to submit a soft copy of the same, by way of a CD, attached to the original Bids..
 - a. Technical proposal - 2 copies (01 original/01 duplicate) & CD
 - b. Financial proposal - 2 copies (01 original/01 duplicate) & CD

ELIGIBILITY CRITERIA

1. Qualification Criteria

- I. Bidder should be a registered company and should be a manufacture or supplier of Hardware solution for similar project last 2 years.
- II. The bidder should be a profit-making company/firm during last 3 consecutive financial years.
- III. Bidders should undertake to supply mentioned solution under this RFP within 6 weeks from the date of acceptance of PO including Pre Delivery Installation (PDI.)
- IV. The Bidder should have the facility to maintain the Hardware Solution to Bank and provide the service 24x7 support on receipt of complaint from the Bank immediately as requested.
- V. Bidder should maintain a stock of spare parts/complete hardware devices with application support to fulfill the bank's requirement.
- VI. Bidder should provide partnership / authorization letters from the manufacturer and partnership status (Platinum/Gold/Silver).
- VII. HDFC Bank does not bind itself to accept the lowest or any tender and reserves the right to reject all or any bid or cancel the Tender without assigning any reason whatsoever. HDFC Bank also reserves the right to re-issue the Tender without the Bidders having the right to object to such a re-issue.
- VIII. HDFC Bank reserves the right to accept or reject, in full or in part, any or all the offers without assigning any reason whatsoever.
- IX. Proposals which fail to address each of the submission requirements above and described in RFP document may be deemed non-responsive and will not be further considered. Note that responses to questions must be specifically answered within the context of the submitted proposal. The Bank's evaluation team will not refer to a designated web site, brochure, or other location for the requested information. Responses that utilize references to external materials as an answer will be considered non-responsive.

Data Sheet

DS No.	ITP Reference	Data	Specific Instructions/Requirements
1.		Title of RFP	Supply, Installation, Commissioning, Training and Maintenance of Hardware Solution for Core banking system for the HDFC Bank of Sri Lanka.
2.		Date & Number of the RFP	14 th June 2021 HDFCB/AD/PRO/RFP/S/2021/06/ 01
3.		Value and validity of the Proposal Guarantee	LKR50,000.00 and valid up to 120 days from the date of closing of proposal.
4.		Deadline for Issuing of RFP Document	02 nd July 2021 - 3.00pm
5.		Validity of Performance Guarantee	Valid up to 45 Calendar Days beyond the Intended Completion date of the period under the Agreement.
6.		Deadline for submitting requests for clarifications / questions	On or before 3.00pm , 20 th July 2021
7.		Number of copies	Technical proposal - 2 copies (01 original/01 duplicate) & CD Financial proposal - 2 copies (01 original/01 duplicate) & CD
8.		Contact Details for submitting clarifications / questions	Contact Party: Neel Adikari Head of IT. HDFC Bank of Sri Lanka, P.O.Box 2085 Sir Chittampalam A. Gardiner Mawatha Colombo 2 TP: 0112356826 M: 0715881617 neel.adikari@hdfc.lk www.hdfc.lk Kasun P.De Silva Chief Manager – IS IT Division HDFC Bank of Sri Lanka P.O.Box 2085, Sir Chittampalam A.Gardiner Mawatha Colombo 2 M: (+94) 711 337 837 D: (+94) 112356812 kasun@hdfc.lk www.hdfc.lk

9.	Required Documents that must be submitted to Establish Eligibility and Qualification of Proponents (in "Certified True Copy" form only)	<ul style="list-style-type: none"> (i) Company Profile. (ii) Members of the Governing Board and their Designations duly certified by the Corporate Secretary. (iii) Certificate of Registration of the business, including Articles of Incorporation, or equivalent document if Party(ies) is not a corporation. (iv) Latest Audited Financial Statement (Income Statement and Balance Sheet) including Auditor's Report for the past 3 consecutive years up to 31st March 2021. (v) All information regarding any past and current litigation during the last five (5) years, in which the Party(ies) is involved, indicating the Party(ies) concerned the subject of the litigation, the amounts involved, and the final resolution if already concluded. (vi) original letter from Principal vendors as a authorize dealer
10.	Period of Proposal Validity commencing on the submission date	Up to 90 days
11.	Deadline of Proposal Submission	On or before 2.00pm 26 th July 2021
12.	Proposal Submission Address	Secretary of the Tender Board II . HDFC Bank, P.O.Box 2085, Sir Chittampalam A.Gardiner Mawatha Colombo 2
13.	Date, time and venue for opening of Proposals	2.00pm 26 th July 2021 HDFC Bank, P.O.Box 2085, Sir Chittampalam A.Gardiner Mawatha Colombo 2 , Sri Lanka.
14.	Signing of Agreement	Within 07 days from the date of issuance of Letter of Acceptance by HDFC BANK.